



Material Content Data Sheet



Sales Product Name		IPP04CN10N G		Issued		29. August 2013			
MA#		MA000840110							
Package		PG-TO220-3-1		Weight*		2038.18 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	17.562	0.86	0.86	8617	8617	
leadframe	non noble metal	iron	7439-89-6	1.407	0.07		690		
	inorganic material	phosphorus	7723-14-0	0.422	0.02		207		
	non noble metal	copper	7440-50-8	1404.801	68.93	69.02	689243	690140	
wire	non noble metal	aluminium	7429-90-5	10.744	0.53	0.53	5271	5271	
encapsulation	organic material	carbon black	1333-86-4	5.743	0.28		2818		
	plastics	epoxy resin	-	109.125	5.35		53541		
	inorganic material	silicondioxide	60676-86-0	459.476	22.54	28.17	225434	281793	
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10530	10530	
plating	non noble metal	nickel	7440-02-0	0.244	0.01		120		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	120	
solder	non noble metal	antimony	7440-36-0	0.719	0.04		353		
	noble metal	silver	7440-22-4	1.799	0.09		882		
	non noble metal	tin	7440-31-5	4.676	0.23	0.36	2294	3529	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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